

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An electronic component comprising:
  - ~~a substrate having a through hole formed in a thickness direction thereof; and~~
  - ~~a conductor, disposed in the through hole, for electrically connecting one side of the substrate to the other side thereof;~~
  - ~~wherein the through hole has a major axis diameter and a minor axis diameter on at least one of one side and the other side of the substrate;~~
  - ~~wherein the through hole comprises a plurality of holes arranged along the thickness direction of the substrate;~~
  - ~~wherein the holes formed adjacent each other in the thickness direction of the substrate have respective center axes shifted from each other as seen in a predetermined direction orthogonal to the thickness direction of the substrate; and~~
  - ~~wherein the predetermined direction orthogonal to the thickness direction of the substrate is the minor axis direction of the through hole.~~
  - a substrate having multiple layers,
  - each layer having one or more through-holes,
  - each through-hole having a conductor disposed therein for electrically connecting one surface of the layer to the other surface of the layer,
  - and each through-hole having a major axis diameter and a minor axis diameter on at least one surface of the layer,
  - wherein the through-holes in a layer are shifted in location so as to not overlap the through-holes in each adjacent layer,

and wherein the directional orientation of the major and minor axes of the through-holes in each layer are the same as the directional orientation of the major and minor axes of the through-holes in adjacent layers.

2. (Previously Presented) The electronic component according to claim 1, wherein the through hole has a form satisfying

$$1 < (D3/D4) \leq 5$$

where D3 is the major axis diameter on the one side, and D4 is the minor axis diameter on the one side.

3. (Previously Presented) The electronic component according to claim 1, wherein the through hole has a form satisfying

$$0.4 \leq (D5/D4) \leq 0.94$$

where D4 is the minor axis diameter on the one side, and D5 is the minor axis diameter on the other side.

4-6 (Canceled)

7. (Currently Amended) The electronic component according to claim 1, further comprising one or more a plurality of conductive films arranged on one or more surfaces of the layers with a gap therebetween extending in the thickness direction of the substrate; and substrate, wherein the conductor electrically connects the conductive films to each other.

8. (Previously Presented) The electronic component according to claim 7, wherein the through hole has a length D0 of

$$D0 \leq 500 \mu\text{m}$$

in each conductive film as seen in a minor axis direction.

9. (Previously Presented) The electronic component according to claim 7, wherein the through hole is formed so as to have a major axis direction extending along a longitudinal direction of the conductive films.

10. (Previously Presented) The electronic component according to claim 7, wherein the conductive film comprises a first electrode film, a first terminal electrode film, a second electrode film, and a second terminal electrode film;

wherein the first electrode film and first terminal electrode film are disposed at the same position as seen in the thickness direction of the substrate with a first insulating gap therebetween;

wherein the second electrode film and second terminal electrode film are disposed at the same position as seen in the thickness direction of the substrate with a second insulating gap therebetween;

wherein the second electrode film opposes the first electrode film and first terminal electrode film by way of the substrate;

wherein the second terminal electrode film opposes the first electrode film by way of the substrate;

wherein the conductor includes a first conductor and a second conductor;

wherein the first conductor electrically connects the first electrode film and the second terminal electrode film to each other; and

wherein the second conductor electrically connects the second electrode film and the first terminal electrode film to each other.

11. (Previously Presented) The electronic component according to claim 10, wherein a group of the first electrode film and first terminal electrode film and a group of the second electrode film and second terminal electrode film are alternately disposed within the substrate with a gap in the thickness direction of the substrate.

12. (Previously Presented) The electronic component according to claim 1, wherein the substrate comprises a piezoelectric material and functions as an actuator.
13. (New) The electronic component according to claim 12, wherein a region overlapping in the substrate with the first electrode film and the second electrode film functions as an active region of the actuator.
14. (New) The electronic component according to claim 1, wherein the major axes of the through-holes in each layer are aligned with the major axes of the through-holes in adjacent layer.